

Afternoon		Special Session — Hardware Collaboration	Venue Mezzanine A+B 13/F			
Time	Duration	Topic	Speaker	Association	Chair	
13:30	00:30	Win-Win Solution for Semiconductor Hardware-Makers and Device-Manufacturers	J.R. Pai 白峻榮	tsmc	Louis Liu 劉旭水	
14:00	00:30	Integrating Existing Capabilities of Local Companies for Making Critical Spare Parts to Meet Logistic Demand of Semiconductor Industry	Bob Chen 陳漢穎	WavePower 宏碩		
14:30	00:30	Think Big, Act Small, Learn Rapidly and Build for longterm	John Wing 溫健宗	Evest 元利盛		
15:00	00:30	EFEM total solution for next generation process	Young Y.H. Hung 洪陽浩	Hirata 平田		
15:30	00:30	Break				
16:00	00:30	Experiences in the making of electronic machines	Lance Wang 王少甫	CTTEK 程泰	Louis Liu 劉旭水	
16:30	00:30	Applications of laser drilling techniques 雷射鑽孔技術簡介與應用	Y.P. Chen 陳育斌	TongTai 東台		
17:00	00:30	Importance of Precision Parts Cleaning for Sub -20nm Technology Nodes	Ardeshir Sidhwa	QuantumClean		
17:30		Adjourn				